

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Original) A communication module comprising:
a semiconductor member;
a flexible printed circuit board on which said semiconductor member is mounted
and to which said semiconductor member is electrically connected;
a stem through which said board is inserted and to which said board is then fixed;
and
a cap so disposed as to cover said semiconductor member.
2. (Original) The communication module according to Claim 1, wherein the semiconductor member is at least one of a light emitting element, a light receiving element and an integrated circuit.
3. (Currently Amended) The communication module according to Claim 1 ~~or 2~~, wherein the flexible printed circuit board includes a type of lines selected from among coplanar lines, micro-strip lines, and grounded coplanar lines.
4. (Currently Amended) The communication module according to Claim 1 ~~any one of Claims 1 through 3~~, wherein a plurality of different flexible printed circuit boards are fixed to the stem.

5. (Currently Amended) The communication module according to Claim 1 ~~any one of Claims 1 through 4~~, wherein an end of the flexible printed circuit board(s) that protrudes from the stem has a connector that can connect to a subsequent-stage circuit board.

6. (Currently Amended) The communication module according to Claim 1 ~~any one of Claims 1 through 5~~, wherein the flexible printed circuit board(s) exhibits a bent-shape when in a plane.